

ABSTRACT OF THE DISCLOSURE

A semiconductor laser module comprising, a semiconductor laser element, an electronic cooling element configured to allow heat from the semiconductor laser element to be transmitted thereto, a heat sink configured to allow the heat which is transmitted to the electronic cooling element to be released, an optical system configured to conduct a laser beam which is emitted from the semiconductor laser element to an optical fiber cable, and a heat resistance section configured to transmit the heat of the optical system to the electronic cooling element, having a heat resistance greater than a heat resistance when the heat of the semiconductor laser element is transmitted to the electronic cooling element.